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# TECHNICAL SPECIFICATION

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**Guidelines for principal component reliability testing for LED light sources and LED luminaires**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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## CONTENTS

FOREWORD.....	6
INTRODUCTION.....	8
1 Scope.....	9
2 Normative references .....	9
3 Terms and definitions .....	10
4 Component test conditions .....	13
5 LED package and interconnects .....	14
5.1 General.....	14
5.2 Sampling requirements .....	14
5.3 Production requirements .....	14
5.4 Assembly of LED packages on test boards.....	15
5.5 Moisture preconditioning .....	15
5.6 Thermal characteristics .....	15
5.7 Pre- and post-stress electrical and photometric requirements .....	15
5.8 Pre- and post-stress visual inspection.....	15
5.9 Solderability and resistance to soldering heat .....	15
5.9.1 Solderability.....	15
5.9.2 Resistance to soldering heat (RSH-reflow) test.....	15
5.10 Failure criteria.....	16
5.11 Initial qualification tests for LED packages .....	16
5.11.1 General .....	16
5.11.2 Temperature and operation stress .....	17
5.11.3 Thermo-mechanical stress.....	18
5.11.4 Temperature and humidity stress.....	18
5.11.5 Electrical stress – ESD-HBM .....	19
5.11.6 Environmental stress .....	19
5.12 Initial qualification test for LED package interconnects – VVF .....	20
5.13 Accelerated stress tests for LED package interconnects .....	20
5.13.1 General .....	20
5.13.2 Interconnect temperature cycling (TMCL) .....	21
6 Optical materials.....	21
6.1 General.....	21
6.2 Optical material test samples .....	22
6.3 Moisture preconditioning .....	22
6.4 Pre- and post-stress photometric measurements.....	22
6.5 Adhesion test.....	23
6.6 Pre- and post-stress visual inspection.....	23
6.7 Failure criteria.....	23
6.8 Initial qualification tests .....	23
6.8.1 Relative humidity (RH).....	23
6.8.2 Boiling water (BW).....	24
6.8.3 Oven water (OW).....	24
6.8.4 High temperature exposure (HTE) .....	24
6.9 Accelerated stress tests.....	24
6.9.1 Prediction models .....	24
6.9.2 Temperature and humidity (TH) .....	25

6.9.3	Temperature and light exposure (TL)	25
6.10	Light-transmitting materials	26
6.11	Light-reflecting materials	26
6.11.1	Dichroic-coated glass and aluminium-coated glass	26
6.11.2	Aluminium-coated plastic	26
6.11.3	White plastic/non-coated plastic	26
6.12	Optical converters	27
7	Electronic subassemblies	27
7.1	General	27
7.2	Sampling requirements	27
7.3	Production requirements	27
7.4	Pre- and post-stress electrical requirements	28
7.5	Pre- and post-stress visual inspection	28
7.6	Failure criteria	28
7.7	Initial qualification tests	28
7.7.1	Temperature and operation stress (PTC)	28
7.7.2	Humidity and operation stress (HOT)	29
7.8	Accelerated stress tests	29
7.8.1	Prediction models	29
7.8.2	Temperature, humidity and operation stress (sequential ALT)	29
8	Active and passive cooling systems	30
8.1	General	30
8.2	Cooling system test samples	31
8.3	Moisture preconditioning	32
8.4	Thermal resistance test	32
8.5	Performance parameter test	32
8.6	Pre- and post-stress cooling performance requirements	32
8.7	Pre- and post-stress visual inspection	32
8.8	Failure criteria	32
8.9	Initial qualification tests	33
8.9.1	General	33
8.9.2	Dust	33
8.10	Accelerated stress tests	34
8.10.1	General	34
8.10.2	Cyclic temperature test (CT) with humidity and with/without operational stress	34
8.10.3	Temperature life test (TLT) passive cooling system	34
8.10.4	Temperature life test (TLT) active cooling system	35
9	Construction materials	35
9.1	General	35
9.2	Mechanical components and interconnects	36
9.3	Mechanical interfaces between different components	36
9.4	Chemical interactions	37
10	Final product testing	38
10.1	General	38
10.2	Principal component reliability in the final product	38
10.3	Minimum validated AST time	39
10.4	Final product qualification for reliability	40
11	Product updates	40

Annex A (informative) Application profiles.....	42
Annex B (informative) Acceleration models.....	43
B.1 General.....	43
B.2 Arrhenius model.....	43
B.3 Eyring model.....	44
B.4 Coffin-Manson model.....	44
B.5 Norris-Landzberg model.....	44
B.6 (Inverse) power law.....	45
B.7 Peck model.....	45
B.8 Generalized Eyring model.....	45
B.9 Sample size calculation.....	46
B.10 Basic guidelines.....	47
B.11 Example.....	47
Annex C (informative) System reliability.....	49
C.1 General.....	49
C.2 Basic principles.....	49
C.3 Testing on the system level.....	49
C.4 System reliability prediction.....	50
C.4.1 General.....	50
C.4.2 Block diagrams.....	50
C.4.3 Fault tree.....	51
C.4.4 Markov chains.....	51
C.4.5 Bayesian networks.....	51
C.4.6 Chi-square.....	52
Annex D (informative) Qualification flowcharts.....	54
D.1 General.....	54
D.2 Qualification flowcharts of principal components.....	54
Annex E (informative) Physical analysis for principal components.....	59
E.1 General.....	59
E.2 DPA for LED packages and interconnects.....	59
E.3 DPA for optical materials.....	60
E.4 PA for electronics.....	60
E.5 PA for active and passive cooling systems.....	61
E.6 DPA for mechanical.....	61
Annex F (normative) Principal component test report.....	62
Bibliography.....	64
Figure D.1 – Qualification flowchart for LED package and interconnects.....	54
Figure D.2 – Qualification flowchart for optical materials.....	55
Figure D.3 – Qualification flowchart for electronic subassemblies.....	56
Figure D.4 – Qualification flowchart for active and passive cooling systems.....	57
Figure D.5 – Qualification flowchart for construction materials.....	58
Table 1 – Mapping the LED package interconnects qualification tests to the useable acceleration model with typical range of the acceleration factor.....	20
Table 2 – Duration (cycles) of temperature application.....	21
Table 3 – Mapping of the optical-material related accelerated stress tests.....	24

Table 4 – Mapping the electronic subassembly qualification tests to the useable acceleration model with typical range of the acceleration factor .....	29
Table 5 – Example ALT profile for an electronic subassembly .....	30
Table 6 – Examples of stressors, affected part of the cooling systems and its reliability effect. ....	31
Table 7 – Mapping the cooling system qualification tests to the useable acceleration model with typical range of the acceleration factor .....	34
Table 8 – List of undesired chemicals in LED products for general lighting. ....	38
Table 9 – Influence of the principal components on the final product.....	39
Table 10 – Example list of validated AST times.....	40
Table 11 – Minor and major change list per principal component. ....	41
Table A.1 – Example of two application profiles .....	42
Table B.1 – Sample sizes versus confidence and reliability level assuming $L = T \times AF$ .....	47
Table B.2 – Example of calculated acceleration factors.....	48
Table C.1 – Example test scheme and results for Chi-square.....	53
Table F.1 – Example overview reporting format .....	63

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

# GUIDELINES FOR PRINCIPAL COMPONENT RELIABILITY TESTING FOR LED LIGHT SOURCES AND LED LUMINAIRES

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Technical specifications are subject to review within three years of publication to decide whether they can be transformed into International Standards.

IEC TS 62861, which is a Technical Specification, has been prepared by subcommittee 34A: Lamps, of IEC technical committee 34: Lamps and related equipment.

The text of this Technical Specification is based on the following documents:

Enquiry draft	Report on voting
34A/1884/DTS	34A/1966/RVDTS

Full information on the voting for the approval of this technical specification can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- transformed into an International standard,
- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

## INTRODUCTION

LED products depend generally on how balanced its principal components are in terms of their reliability. It is not only the LED components that determine product performance, but also other parts of the LED product play an equally important role. For instance, electronic subassemblies, optics, mechanics and the involved cooling method play such a role.

This Technical Specification envisions a methodology, which addresses separate subcomponent reliability data, to provide a basis for statistical system reliability design. Standardized reporting formats and flowcharts are presented.

Next, protocols based on accelerated methods are given to estimate system reliability of the final product using subcomponent data.

Verification of LED product lifetime is based on a 'test to pass' principle, which means the components of the product under test are evaluated to give equivalent reliability confidence to that which would be achieved by real-time life testing of the complete LED product. The tests described in this Technical Specification are divided into: initial qualification tests (IQT) giving confidence of basic component robustness, but not linked to any specific lifetime projection, and accelerated stress tests (AST) giving confidence of reliability to a specific lifetime (within the specified constraints of the test).

Since the approach foreseen in this Technical Specification covers a generic methodology, it can be seen as guidance related to relevant product performance standards, such as the LED lamp performance standard IEC 62612, the LED module performance standard IEC 62717 and LED luminaire performance standard IEC 62722-2-1. This Technical Specification is not recommended for use as a normative reference to the LED product performance standards.

This Technical Specification addresses the need for a document giving guidance that is developed according to consensus procedures and in itself is normative in nature, while at the same time recognizing that LED technology for lighting products is still in an emerging phase. This Technical Specification approaches an International standard in terms of detail and completeness.



## **GUIDELINES FOR PRINCIPAL COMPONENT RELIABILITY TESTING FOR LED LIGHT SOURCES AND LED LUMINAIRES**

### **1 Scope**

This Technical Specification provides guidelines for establishing confidence in product reliability using principal component testing for LED light sources and LED luminaires for general lighting. It includes methods and criteria using initial qualification tests and accelerated stress tests of the principal components. The performance of any principal component will influence the performance of the final product.

Techniques to validate full lifetime claims and lumen maintenance projection are outside the scope of this Technical Specification.

The following principal components are included in the testing if they are used as an integral part for the LED light source or LED luminaire:

- LED package and interconnects;
- optical materials;
- electronic subassemblies;
- cooling systems, both active (e.g. fans) and passive (e.g. thermal interface material);
- construction materials.

This Technical Specification is not recommended for use as a normative reference to the LED product performance standards.

### **2 Normative references**

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-2-20:2008, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*

IEC 60068-2-27:2008, *Basic environmental testing procedures – Part 2: Tests – Test Ea and guidance: Shock*

IEC 60068-2-30:2005, *Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)*

IEC 60068-2-42:2003, *Environmental testing – Part 2-42: Tests – Test Kc: Sulphur dioxide test for contacts and connections*

IEC 60068-2-43:2003, *Environmental testing – Part 2-43: Tests – Test Kd: Hydrogen sulphide test for contacts and connections*

IEC 60068-2-58:2015, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

IEC 60068-2-60:2015, *Environmental testing – Part 2-60: Tests – Test Ke: Flowing mixed gas corrosion test*

IEC 60529:2013, *Degrees of protection provided by enclosures (IP Code)*

IEC 60929:2011, *AC and/or DC-supplied electronic control gear for tubular fluorescent lamps – Performance requirements*  
IEC 60929:2011/AMD1:2015

IEC 62504, *General lighting – Light emitting diode (LED) products and related equipment – Terms and definitions*

ANSI/ESDA/JEDEC JS-001-2014, *Electrostatic discharge sensitivity testing human body model (HBM) – Component level*

ASTM D5470 – 12, *Standard test method for thermal transmission properties of thermally conductive electrical insulation materials*

ASTM D7027 – 13, *Standard test method for evaluation of scratch resistance of polymeric coatings and plastics using an instrumented scratch machine*

ASTM E595 – 07, *Standard test method for total mass loss and collected volatile condensable materials from outgassing in a vacuum environment*

IPC-9591, *Performance parameters (mechanical, electrical, environmental and quality/reliability) for air moving devices*

J-STD-002D, *Solderability tests for component leads, terminations, lugs, terminals and wires*

J-STD-020E, *Moisture/reflow sensitivity classification for nonhermetic surface mount devices*

JESD22-A101C, *Steady-state temperature humidity bias life test*

JESD22-A104D, *Temperature cycling*

JESD22-A108D, *Temperature, bias, and operating life*

JESD22-A113F, *Preconditioning of plastic surface mount devices prior to reliability testing*

JESD22-B103B, *Vibration, variable frequency*

JESD51-51, *Implementation of the electrical test method (static test method) for the measurement of the real thermal resistance and impedance of light emitting diodes with exposed cooling surface*

MIL-C-48497A, *Durability requirements for coating, single or multilayer, interference*